

Application No.: 10/049,499  
Attorney Docket No.: FUK-89  
Amendment Dated: January 7, 2005  
Reply for Office Action Dated: December 15, 2004

REMARKS

Claims 1-7 are pending in the application and subject to a restriction requirement involving the inventions of Group I (claims 1-5) and Group II (claims 6-7).

Applicant hereby elects the invention of Group I (claims 1-5) for examination and reserves the right to file a continuation application on non-elected claims 6-7.

The Amendments to the Claims reflect the current version of the claims, following entry of the election made herein and entry of the preliminary amendment submitted previously in the filing of June 21, 2002. No other changes are being made herein to the claims.

If the Examiner has any questions or comments that would advance prosecution of this case, the Examiner is invited to call the undersigned at 260/484-4526.

Respectfully Submitted,



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RJK/jrw2

Enclosures: Amendments to the Claims  
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450, on: January 7, 2005.



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AMENDMENTS TO THE CLAIMS

1. (previously presented) A method of producing a multilayered printed-circuit board, comprising steps of:

stacking up a laminated sheet covered with conductive foil or conductor for an outer layer, a prepreg and a laminated sheet covered with conductor for an inner layer; thereafter,

setting the prepreg by pressurizing/heating; and

before conducting the pressurizing/heating, gas is sprayed on the surfaces of the laminated sheet covered with conductive foil or conductor for the outer layer, a prepreg and a laminated sheet covered with conductor for the inner layer to eliminate impurities from the surfaces.

2. (previously presented) The method according to claim 1, wherein said gas is a dried gas.

3. (previously presented) The method according to claim 2, wherein said dry gas is a heated gas.

4. (previously presented) A method of producing a multilayered printed-circuit board, comprising steps of:

preparing a plurality of wiring boards having a circuit formed with conductive foil, and having through holes filled with a through hole conduct; or

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multilayering by pressurizing/heating the plurality of wiring boards each other, and sprayed gas on a surface of the wiring board to eliminate impurities from the wiring board surface before pressurizing/heating.

5. (previously presented) The method according to claim 1, wherein the pressure during said pressurizing step is between 10 to 15 kg/cm<sup>2</sup>.

6. (withdrawn) A apparatus for producing multilayered printed-circuit board, comprising:

a movable table for laminating and pressurizing molded works each other, and

5 a means for heating said molded works, wherein the space for pressurizing the molded works is hermetically sealable and the sealable space is provided with an inlet for introducing gas therein and an outlet for discharging the gas.

7. (withdrawn) The apparatus according to claim 6, wherein said inlet is disposed in parallel to the laminated face of said molded works.